

SOT900-1

plastic thermal enhanced ball grid array package; 456 balls;
body 27 x 27 x 1.75 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA456
Package type industry code	HBGA456
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	2-9-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	26.8	-	27	27.2	mm
E	package width	26.8	-	27	27.2	mm
A	seated height	[tbd]	-	2.45	2.45	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	456	-	

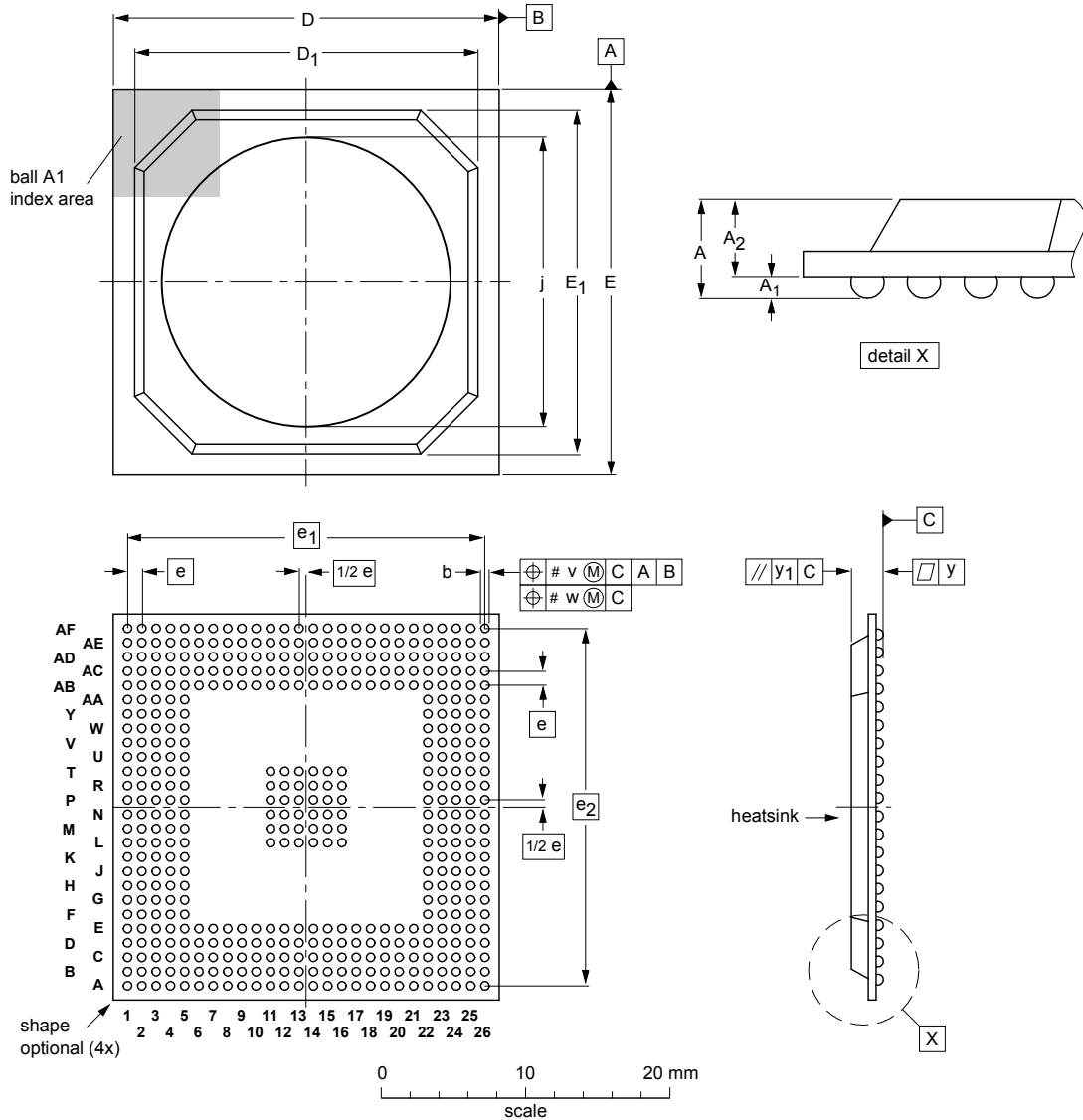


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2. Package outline

HBGA456: plastic thermal enhanced ball grid array package; 456 balls;
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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max.}	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	j	v	w	y	y ₁
mm	2.45	0.6 0.4	1.85 1.60	0.7 0.5	27.2 26.8	24.75 23.75	27.2 26.8	24.75 23.75	1	25	25	22 18	0.25	0.1	0.2	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT900-1	144E	MS-034	---			05-04-11 05-09-02

Fig. 1. Package outline HBGA456 (SOT900-1)

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3. Soldering

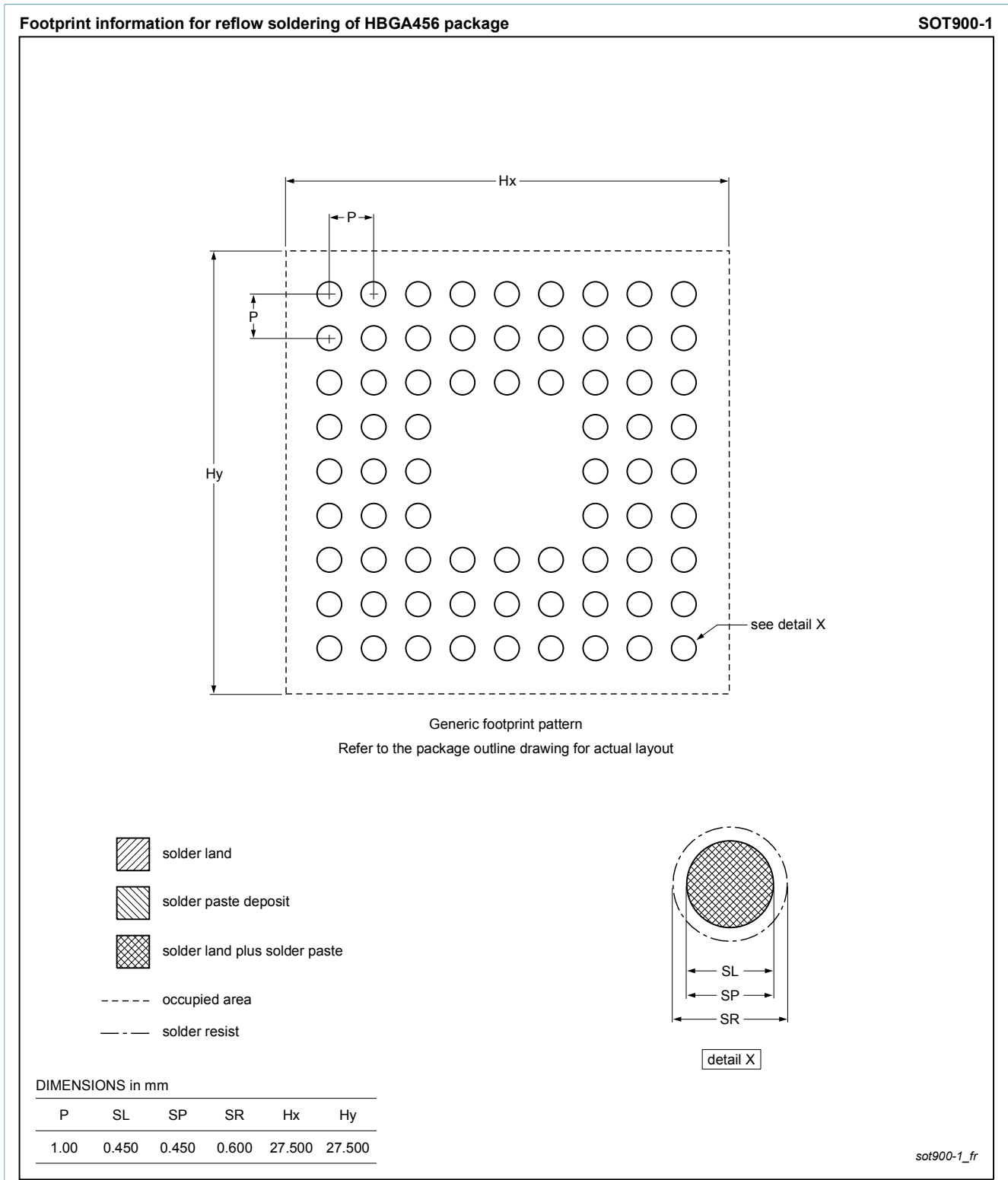


Fig. 2. Reflow soldering footprint for HBGA456 (SOT900-1)

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4. Legal information

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